CLAIMS

1. A resist composition comprising (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains:

(D-1) at least one organic solvent selected from the group consisting of an α-hydroxycarboxylate ester, a β-alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative, and

(D-2) an organic solvent having a hydroxyl group other than (D-1).

2. The resist composition according to claim 1, wherein (D-1) is an α-hydroxycarboxylate ester.

3. The resist composition according to claim 2, wherein the α-hydroxycarboxylate ester is a lactate ester.

4. A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist composition according to any one of claims 1 to 3.

5. A method of producing a print circuit board, which comprises using the resist composition according to any one of claims 1 to 3.

6. A resist composition for dip coating comprising (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains:

(D-1) at least one organic solvent selected from the group consisting of an α-hydroxycarboxylate ester, a β-alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative.

7. A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist composition according to claim 6.

8. A method of producing a print circuit board, which comprises using the resist composition according to claim 6.